

Marking Information



1R6 = SOT23, Product Type Marking Code 3105 = SOT26, Product Type Marking Code YM = Date Code Marking Y or Y = Year (ex: C = 2015) M or M = Month (ex: 9 = September)

Date Code Key

Year	201	5	20	016	2017	2018	2019	2020	202	1 20	22 2	2023	2024	2025
Code	C			D	E	F	G	Н			J	K	L	М
Mont	h	Ja	an	Feb	Mar	Apr	Мау	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	•		1	2	3	4	5	6	7	8	9	0	N	D

Internal Device Schematic







Absolute Maximum Ratings (@T_A = +25 °C, unless otherwise specified.)

Characteristic	Symbol	Limit	Unit
Supply Voltage	V _{CC}	6.0	V
Input Voltage (Forward)	V _{IN(FWD)}	6.0	V
Input Voltage (Reverse)	V _{IN(REV)}	-0.5	V
Output Sink Continuous Current	lo	500	mA
Repetitive Pulse Zener Energy Limit (Duty Cycle 0.01%)	E _{zpk}	50	mJ

Thermal Characteristics for DRDC3105F (SOT23) (@T_A = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit	
Power Dissipation	(Note 5)	D-	310	m\\/	
Power Dissipation	(Note 6)	гD	350	11177	
Thermal Resistance, Junction to Ambient	(Note 5)	D	403	°C M/	
Thermal Resistance, Junction to Ambient	(Note 6)	Reja	357	0/11	
Thermal Resistance, Junction to Leads	(Note 11)	$R_{\theta JL}$	350	°C/W	
Operating and Storage Temperature Range		TJ, TSTG	-55 to +150	C	

Thermal Characteristics for DRDC3105E6 (SOT26) (@T_A = +25 °C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit	
	(Notes 7 & 9)		0.9 7.2		
Power Dissipation Linear Derating Factor	(Notes 7 & 10)	P _D	1.1 8.8	W mW/℃	
	(Notes 8 & 10)		1.7 13.6		
	(Notes 7 & 9)		139	°C/W	
Thermal Resistance, Junction to Ambient	(Notes 7 & 10)	R _{0JA}	113		
	(Notes 8 & 10)		73		
Thermal Resistance, Junction to Leads	(Note 11)	R _{0JL}	100	°C/W	
Operating and Storage Temperature Range	TJ, T _{STG}	-55 to +150	C		

5. For a device mounted on minimum recommended pad layout 1oz weight copper that is on a single-sided FR4 PCB; device is measured under still air Notes: For a device mounted on minimum recommended pad layout 102 weight copper conditions whilst operating in a steady-state.
Same as Note 5, except the device is mounted on 15mm X 15mm 1oz copper.
Same as Note 5, except the device is mounted on 25mm X 25mm 1oz copper.
Same as Note 7, except the device is measured at < 5 seconds.
For a device with one active die.

For a device with two die running at equal power.
Thermal resistance from junction to solder-point (at the end of the "OUT" lead).





Electrical Characteristics (@T_A = +25 °C, unless otherwise specified.)

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	Symbol	win	тур	мах	Unit	lest Condition
OFF CHARACTERISTICS	51				1	1
Output Zener Breakdown Voltage	BV _(out)	6.2	6.6	7.0	V	@ Iτ = 10 mA Pulse
	BV _(-out)	-	0.67	-		
Output Leakage Current @ 0 Input Voltage	loo	—	_	0.1	uА	V _O = 5.5 V, T _A = +25 ℃
	100	—		30	Pre -	V _O = 5.5 V, T _A = +85 ℃
"ON" State Input Voltage (Note 12)	V _{in(on)}	—	0.99	1.5	V	I _O =100 mA, V _O = 150mV
"OFF" State Input Voltage (Note 13)	Vin(off)	400	540	—	mV	I _O =100 μA, V _O = 4.9V
ON CHARACTERISTICS						
Input Bias Current (HFE Limited)	l _{in}	—	0.7	1.6	mA	I _O = 250 mA, V _O = 0.25V
Output Saturation Voltage	V _{O(sat)}	_	125	160	mV	I _O = 250 mA, I _{in} = 1.5 mA
Output Sink Current – Continuous	I _{O(on)}	250	430	—	mA	V _{CE} = 0.25 V, I _{in} = 1.5 mA
SWITCHING CHARACTERISTICS (Refer to Figure	1)					·
Propagation Delay Times:						
High to Low Propagation Delay; (5.0V 74HC04)	t PHL		20.4		ns	
Low to High Propagation Delay; (5.0V 74HC04)	t PLH	_	1.43	_	μs	_
High to Low Propagation Delay; 13 (3.0V 74HC04)	t _{PHL}		32.2		ns	
Low to High Propagation Delay; 13 (3.0V 74HC04)	t _{PLH}	_	760	_	ns	_
High to Low Propagation Delay; 14 (5.0V 74LS04)	t _{PHL}		25.3		ns	
Low to High Propagation Delay; 14 (5.0V 74LS04)	t PLH	_	2.57	_	μs	_
Transition Times:	•					·
Fall Time; (5.0V 74HC04)	t _f		12.5		ns	
Rise Time; (5.0V 74HC04)	tr	_	411	_	ns	_
Fall Time; 13 (3.0V 74HC04)	t _f		21.1		ns	
Rise Time; 13 (3.0V 74HC04)	tr	_	220	_	ns	_
Fall Time; 14 (5.0V 74LS04)	t _f		15.1		ns	
Rise Time; 14 (5.0V 74LS04)	tr	_	849	_	ns	

12. The device is guaranteed to be in "ON" state with $V_{\rm IN(ON)}$ above 1.5V. 13. The device is guaranteed to be in "OFF" state with $V_{\rm IN(OFF)}$ below 400mV. Notes:



Figure 1. Switching Waveforms



Typical Electrical Characteristics (@ $T_A = +25 \,^{\circ}C$, unless otherwise specified.)



Figure 2. Transistor DC Current Gain



Figure 4. Threshold Effects







Figure 3. Input V-I Requirement Compared to Possible Source Logic Outputs



Figure 5. Transistor Output V-I Characteristic











Figure 10. Safe Operating Area











Figure 12. Transient Thermal Response



Package Outline Dimensions

Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version.

Package Type: SOT23



SOT23					
Dim	Min	Max	Тур		
Α	0.37	0.51	0.40		
В	1.20	1.40	1.30		
С	2.30	2.50	2.40		
D	0.89	1.03	0.915		
F	0.45	0.60	0.535		
G	1.78	2.05	1.83		
Н	2.80	3.00	2.90		
J	0.013	0.10	0.05		
К	0.890	1.00	0.975		
K1	0.903	1.10	1.025		
L	0.45	0.61	0.55		
L1	0.25	0.55	0.40		
М	0.085	0.150	0.110		
а	8°				
All Dimensions in mm					

Package Type: SOT26



SOT26						
Dim	Min	Max	Тур			
A1	0.013	0.10	0.05			
A2	1.00	1.30	1.10			
A3	0.70	0.80	0.75			
b	0.35	0.50	0.38			
С	0.10	0.20	0.15			
D	2.90	3.10	3.00			
e	-	-	0.95			
e1	-	-	1.90			
Е	2.70	3.00	2.80			
E1	1.50	1.70	1.60			
L	0.35	0.55	0.40			
а	-	-	8°			
a1	-	-	7°			
All	Dimen	sions	in mm			



Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.

Package Type: SOT23



Dimensions	Value (in mm)		
Z	2.9		
Х	0.8		
Y	0.9		
С	2.0		
E	1.35		

Package Type: SOT26



Dimensions	Value (in mm)
C	2.40
C1	0.95
G	1.60
X	0.55
Y	0.80
Y1	3.20



DRDC3105

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